TG-G1.5-01

Heatsink thermal paste grease, 1.5 g weight

- Keep your computer's CPU cool
- Practical syringe for easy application



Features

- Thermal compund (grease) for heatsinks
- Helps the heat dissipation from a CPU, chipset or processor to a heatsink
- Excellent thermal impedance
- Perfect stability will not separate, run, migrate, or bleed
- Non capacitive or electrically conductive

Specifications

Weight: 1.5 g
Color: grey
Thermal conductivity: > 4.5 W / mK
Thermal Impedance <0.205 ° C-in2 / W
Density: > 2.5
Evaporation: <0.001 %
Volatility: <0.005 %
The dielectric constant: > 5.1
Dissipation Factor: <0.005
Viscosity: 76 CPS
Thixotropic index: 310 ± 10 ° C
Operating Temperature: -50 ~ 240 ° C
Composites: 50% silicone compounds
Compounds: 30% of carbon
The compounds of metal oxides: 20%

Packaging

Q'ty in crtn, pcs	100
Crtn volume, CUM	0.02
Crtn weight, kgs	1.93
Individual package size LxWxH:	150x60x20 mm
Carton size LxWxH:	330x330x180 mm
Country of origin	CN
Barcode	8716309083126
Customs code	3402909000

Certificates

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